



# FORMAPad® GI-5100

Dispensable Form in  
Place Thermal Pad



## Description

FORMAPad® GI5100 is specially formulated to offer excellent wetting and minimum pump out property with tacky texture. Dispensable and screen printable consistency makes easy in production environment. Offers excellent stability over a wide temperature range with high thermal conductivity and low thermal resistance. It's a high performance thermal grease designed to meet the thermal, reliability and low price requirements of high-end chipset, graphic processors trend ever-faster clock speeds. RoHS compliant and halogen-free.



## Characteristics

- High Thermal Conductivity (2.6 W/m-K)
- Tacky, Thixotropic Paste
- Excellent wetting property
- RoHS Compliant-Halogen Free
- Thin Bond line Thickness <25 micron

## Applications

- Interface for semiconductors requiring low pressure or spring clamp mounting
- Thermal sensors, TEC modules, Thermal Wells
- IGBT's, LED
- Power Transistors, Diodes, Power Resistors
- CPU/GPU/Heat Sink



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**CELERA**  
Passion for Technique

## Typical Property

Property	Test Method	Unit	Results
Color	-	-	Grey
Operating Temperature Range	-	-	55°C to 205°C
Viscosity	Helipath	5rpm @25°C, PaS	550
Specific Gravity	ASTM D792	g/cm <sup>3</sup>	2,20
Thermal Conductivity	ASTM D5470	W/m.k	2,60
Thermal Resistance	ASTM D5470	C-in <sup>2</sup> /W	0,01
Breakdown Voltage	ASTM D149	kV/mm	2,8
Dissipation Factor	ASTM D150	1KHz	0,1277
Volume Resistivity	ASTM D257	Ohm.cm	10 <sup>-09</sup>
Shelf Life	@ 25°C	-	5 years